



# 200324741 Availability of Si5332 Rev1.3 Datasheet, Updated 40/48-LGA Package Designs

**PCN Issue Date:** 3/24/2020

**Effective Date:** 6/30/2020

**PCN Type:** Datasheet; Other

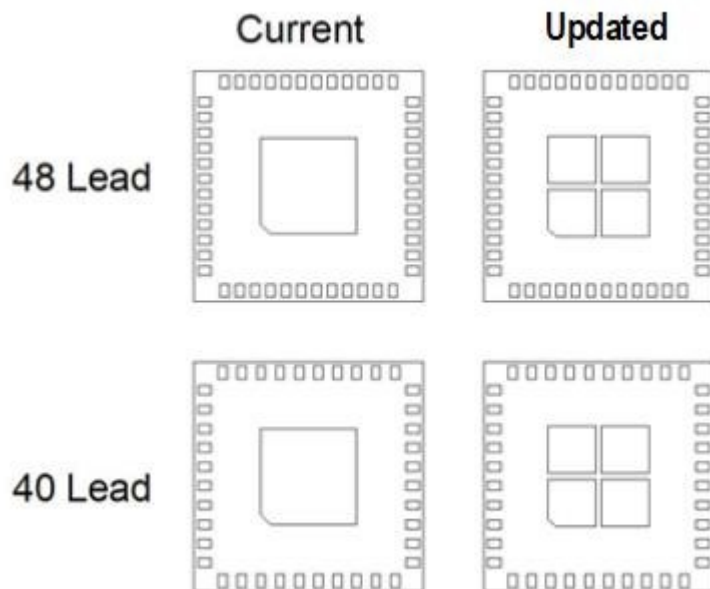
## Description of Change

Silicon Labs is pleased to announce the availability of revision 1.3 of the Si5332 datasheet.

## Reason for Change

The following changes were made to the datasheet:

- Added new Si5332L ordering option, featuring integrated reference with tighter stability:  $\pm 30$ ppm
- Updated Package Outline Drawing for 40-pin 6x6mm LGA package, partitioning the center ground epad into a 2x2 grid array.
- Updated PCB Land Pattern Drawing stencil design recommendations for 40-pin 6x6mm LGA package.
- Updated Package Outline Drawing for 48-pin 6x6mm LGA package, partitioning the center ground epad into a 2x2 grid array.
- Updated PCB Land Pattern Drawing stencil design recommendations for 48-pin 6x6mm LGA package.



## Package Lead Changes

## Impact on Form, Fit, Function, Quality, Reliability

There is no impact on fit or function.

#### Form

In an effort to improve product quality, the 40-pin 6x6mm and 48-pin 6x6mm LGA packages used with Si5332E/F/G/H/L-grade devices are being updated. The single, center ground epad has been partitioned into a 2x2 grid array, divided with solder resist into 4 pads to increase mechanical support to the center of the package. There is no change made to any of the metal layers of the package. Revision 1.3 of the Si5332 datasheet includes the new, updated 40-pin and 48-pin 6x6mm LGA package outline drawings, partitioning the center ground epad into a 2x2 grid array, as shown above.

The PCB land pattern drawing stencil design notes for 40-pin and 48-pin 6x6mm LGA packages have been updated in revision 1.3 of the Si5332 datasheet to reflect the updated 2x2 grid ground pad array.

A review of the SMT stencil apertures on all designs that use Si5332E/F/G/H/L-grade devices in 40-pin and 48-pin LGA packages must be performed. Stencil updates to existing designs may be necessary to match the new 2x2 grid-array package patterns.

#### Last Date of Unchanged Product:

Silicon Labs will migrate all production orders of Si5332E/F/G/H/L-grade devices in 40-pin and 48-pin LGA packages from the current single-center epad design to the updated, partitioned 2x2 grid array in WW28. All production orders shipped prior to WW28 will use the current single-center epad design. All orders shipped after WW28 will use the new, updated 2x2 grid ground pad array design.

## Product Identification

Existing Part #  
Si5332E-D-GM2  
Si5332F-D-GM2  
Si5332G-D-GM2  
Si5332H-D-GM2  
Si5332L-D-GM2  
Si5332EDxxxxx-GM2  
Si5332FDxxxxx-GM2  
Si5332GDxxxxx-GM2  
Si5332HDxxxxx-GM2  
Si5332LDxxxxx-GM2  
Si5332E-D-GM3  
Si5332F-D-GM3  
Si5332G-D-GM3  
Si5332H-D-GM3  
Si5332L-D-GM2  
Si5332EDxxxxx-GM3  
Si5332FDxxxxx-GM3  
Si5332GDxxxxx-GM3  
Si5332HDxxxxx-GM3  
Si5332LDxxxxx-GM3

**Last Date of Unchanged Product:** 6/30/2020

## Qualification Samples

Available upon request.

## Customer Response

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change, Ref. JEDEC-J-STD-046.

To request further data or inquire about this notification, please contact your Silicon Labs sales representative. A list of Silicon Labs sales representatives is available at <http://www.silabs.com>.

Customers may approve early PCN acceptance by emailing approval, along with PCN # to [PCNEarlyAcceptance@silabs.com](mailto:PCNEarlyAcceptance@silabs.com)

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## Qualification Data

See attached.

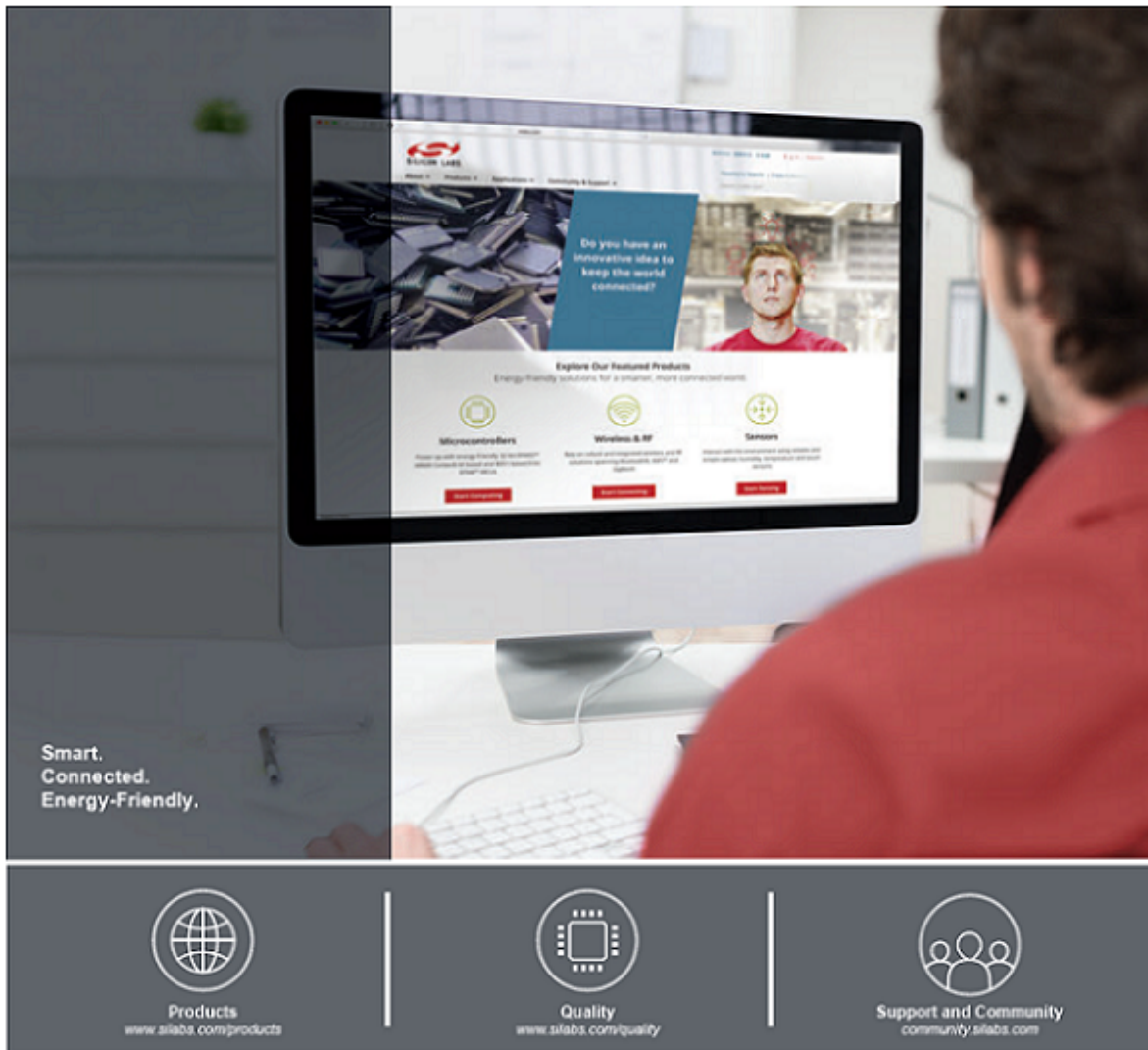
Part Rev D, TSMC Fabrication, ASECL Assembly except as noted							
Test Name	Test Condition	Qualification	Lot ID or Start	Fail/Pass or End	Notes	Summary	Status
<b>Test Group A – Accelerated Environment Stress Tests - 40/48-Pin 6x6 mm LGA</b>							
HAST	JA110 110°C, 85%RH Vcc=3.3V, 264 hours	3 lots, N=>25	Q042577	0/25	1	3 lots 0/75	Pass
			Q042578	0/25	1		
			Q042579	0/25	1		
Temp Cycle	JA104 Cond C: -85°C to 150°C 500 cycles	3 lots, N=>25	Q045442	0/25	1	3 lots 0/75	Pass
			Q045443	0/25	1		
			Q045444	0/25	1		
HTSL	JA103 150°C, 1000hr	3 lots, N=>25	Q042580	0/25	1	3 lots 0/75	Pass
			Q042581	0/25	1		
			Q042582	0/25	1		
<b>Test Group A – Accelerated Environment Stress Tests - 32-Pin 5x5 mm LGA</b>							
HAST	JA110 110°C, 85%RH Vcc=3.3V, 264 hours	3 lots, N=>25	Q042586	0/25	1	3 lots 0/75	Pass
			Q042587	0/25	1		
			Q042588	0/25	1		
Temp Cycle	JA104 Cond C: -85°C to 150°C 500 cycles	3 lots, N=>25	Q042592	0/25	1	3 lots 0/75	Pass
			Q042593	0/25	1		
			Q042594	0/25	1		
HTSL	JA103 150°C, 1000hr	3 lots, N=>25	Q042589	0/25	1	3 lots 0/75	Pass
			Q042590	0/25	1		
			Q042591	0/25	1		
<b>Test Group B – Accelerated Lifetime Simulation Tests</b>							
HTOL	JA108 T <sub>J</sub> ≥ 125°C, Dynamic Vcc=3.3V, 1000 hours	3 lots, N=>77	Q040841	0/80	2	3 lots 0/240	Pass
			Q041408	0/80	2		
			Q042772	0/80	2		
LTOL	JA108 T <sub>A</sub> = -10°C, Dynamic Vcc=3.3V, 1000 hours	1 lot, N=>32	Q035769	0/34	2	1 lots 0/34	Pass
ELFR	JA108 T <sub>J</sub> ≥ 125°C, Dynamic Vcc=3.3V, 48 hours	3 lots, N=>500	Q040840	0/504	2	3 lots 0/1512	Pass
			Q041018	0/504	2		
			Q042762	0/504	2		
<b>Test Group C – Package Assembly Integrity Tests - 40/48-Pin 6x6 mm LGA</b>							
Mechanical Shock	JB104 Condition B, 1,500g	3 lots, N=>39	Q042708	0/40		3 lots 0/120	Pass
			Q042711	0/40			
			Q042714	0/40			
Mechanical Vibration	JB103 Condition 1, 20g	3 lots, N=>39	Q042709	0/40		3 lots 0/120	Pass
			Q042712	0/40			
			Q042715	0/40			
Constant Acceleration	M2001 Condition B, 10,000g	3 lots, N=>39	Q042710	0/40		3 lots 0/120	Pass
			Q042713	0/40			
			Q042716	0/40			

Part Rev D, TSMC Fabrication, ASECL Assembly except as noted							
Test Name	Test Condition	Qualification	Lot ID of Start	Fail/Pass of End	Notes	Summary	Status
<b>Test Group C – Package Assembly Integrity Tests - 32-Pin 5x5 mm LGA</b>							
Mechanical Shock	JB104 Condition B, 1,500g	3 lots, N=>39	Q042717	0/40		3 lots 0/120	Pass
			Q042720	0/40			
			Q042723	0/40			
Mechanical Vibration	JB103 Condition 1, 20g	3 lots, N=>39	Q042718	0/40		3 lots 0/120	Pass
			Q042721	0/40			
			Q042724	0/40			
Constant Acceleration	M2001 Condition B, 10,000g	3 lots, N=>39	Q042719	0/40		3 lots 0/120	Pass
			Q042722	0/40			
			Q042725	0/40			
<b>Test Group E – Electrical Verification</b>							
ESD-HBM	JS-001	1 lot, N=>3	Q040754		2	3 kV	Class 2
ESD-CDM	JESD22-C101	1 lot, N=>3	Q042509			500 V	Class III
ESD-CDM	JESD22-C101	1 lot, N=>3	Q042527			750 V	Class III
Latch Up	JESD78 ±100mA Overvoltage = 4.95V	1 lot, N=>3	Q040756	85 °C	2		Pass

Notes:

- Parts are Pre-conditioned at MSL3/260°C
- Leveraged die family qualification data

This report applies to the following part numbers:				
Si5332E-D-GM1	Si5332E-D-GM1R	Si5332E-D-GM2	Si5332E-D-GM2R	Si5332E-D-GM3
Si5332E-D-GM3R	Si5332F-D-GM1	Si5332F-D-GM1R	Si5332F-D-GM2	Si5332F-D-GM2R
Si5332F-D-GM3	Si5332F-D-GM3R	Si5332G-D-GM1	Si5332G-D-GM1R	Si5332G-D-GM2
Si5332G-D-GM2R	Si5332G-D-GM3	Si5332G-D-GM3R	Si5332H-D-GM1	Si5332H-D-GM1R
Si5332H-D-GM2	Si5332H-D-GM2R	Si5332H-D-GM3	Si5332H-D-GM3R	Si5332EDxxxxx-GM1
Si5332EDxxxxx-GM1R	Si5332EDxxxxx-GM2	Si5332EDxxxxx-GM2R	Si5332EDxxxxx-GM3	Si5332EDxxxxx-GM3R
Si5332FDxxxxx-GM1	Si5332FDxxxxx-GM1R	Si5332FDxxxxx-GM2	Si5332FDxxxxx-GM2R	Si5332FDxxxxx-GM3
Si5332FDxxxxx-GM3R	Si5332GDxxxxx-GM1	Si5332GDxxxxx-GM1R	Si5332GDxxxxx-GM2	Si5332GDxxxxx-GM2 R
Si5332GDxxxxx-GM3	Si5332GDxxxxx-GM3R	Si5332HDxxxxx-GM1	Si5332HDxxxxx-GM1R	Si5332HDxxxxx-GM2
Si5332HDxxxxx-GM2R	Si5332HDxxxxx-GM3	Si5332HDxxxxx-GM3R	Si5357ADxxxxx-GM	Si5357ADxxxxx-GMR
Si5332L-D-GM1	Si5332L-D-GM1R	Si5332L-D-GM2	Si5332L-D-GM2R	Si5332L-D-GM3
Si5332L-D-GM3R	Si5332LDxxxxx-GM1	Si5332LDxxxxx-GM1R	Si5332LDxxxxx-GM2	Si5332LDxxxxx-GM2R
Si5332LDxxxxx-GM3	Si5332LDxxxxx-GM3R			



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